PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT4541628

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Tsuo-Wen Lu	08/01/2017
Chin-Wei Wu	08/01/2017
Tien-Chen Chan	08/01/2017
Ger-Pin Lin	08/01/2017
Shu-Yen Chan	08/01/2017

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN
Name:	FUJIAN JINHUA INTEGRATED CIRCUIT CO., LTD.
Street Address:	6TH FLOOR, PODIUM OF ELECTRIC POWER COMPANY BUILDING, MEILING STREET, JINJIANG CITY
City:	QUANZHOU CITY, FUJIAN PROVINCE
State/Country:	CHINA

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15672272

CORRESPONDENCE DATA

Fax Number: (703)997-4517

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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Address Line 4: NEW TAIPEI CITY, TAIWAN

ATTORNEY DOCKET NUMBER:	NAUP3106USA
NAME OF SUBMITTER:	SIBYL YU
SIGNATURE:	/SIBYL YU/

PATENT 504494926 REEL: 043236 FRAME: 0159

DATE SIGNED:	08/08/2017
Total Attachments: 10	
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PATENT REEL: 043236 FRAME: 0160

Title of Invention:

SEMICONDUCTOR DEVICE AND FABRICATION METHOD THEREOF

As the below named inventor, I here This declaration is directed to:	by declare that:				
☑ The attached application, or					
☐ United States application nu	ımber	filed on, or			
☐ PCT international applicatio	n number	filed on	_		
The above-identified application was	made or authorized to be made	by me.			
I believe that I am the original invent application.	or or an original joint inventor of a	a claimed invention in the			
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr					
In consideration of the payment by	UNITED MICROELECTRON	NICS having a postal address	s of		
No.3, Li-Hsin Road 2, Science	-Based Industrial Park, Hsi	in-Chu City 300, Taiwan, R	.o.c.		
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar	o I of the sum of One Dollar (\$ 1.0 ad valuable consideration.	00), the receipt of which is hereby	у		
In consideration of the payment by	Fujian Jinhua Integrated C Co., Ltd.	Circuit having a postal address	s of		
6th floor, Podium of electric p Quanzhou City, Fujian provin		leiling street, Jinjiang city,			
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar	o I of the sum of One Dollar (\$ 1.0 ad valuable consideration.	00), the receipt of which is hereby	у		
I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.					
I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;					
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal					

Page 1 of 10

NPO#NAU-P3106-USA:0 CUST#UMCF-2017-0083

maintain, issue equivalents the	es any and all papers, instruments or affidav e and enforce said application, said inventio ereof which may be necessary or desirable	on and said Le to carry out t	etters Pat	ent and s	said of.
IN WINTNESS	S WHEREOF, I have hereunto set hand and	seal this	AUG 0	1 2017	(Date of signing)
	ication data sheet (PTO/SB/14 or equivalent y, must accompany this form. Use this form				
LEGAL NAME	E OF INVENTOR(ASSIGNOR)				
	suo-Wen Lu	Date:	AUG	0 1 201	7
Signature:	Tsuo-Wen Lu				

Page 2 of 10

NPO#NAU-P3106-USA:0 CUST#UMCF-2017-0083

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The above-identified application was	s made or authorized to be ma	ade by me.		
I believe that I am the original invent application.	tor or an original joint inventor	of a claimed i	nvention in the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	Il false statement made in this isonment of not more than five	declaration is e (5) years, or	punishable both.	
In consideration of the payment by	UNITED MICROELECTS CORP.	RONICS h	aving a postal addı	ess of
No.3, Li-Hsin Road 2, Science	e-Based Industrial Park,	Hsin-Chu C	ity 300, Taiwan,	R.O.C.
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6th floor, Podium of electric p Quanzhou City, Fujian provin	oower company building ce 362200, P.R.C.	, Meiling st	eet, Jinjiang ci	ty,
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar	o I of the sum of One Dollar (\$ nd valuable consideration.	1.00), the red	eipt of which is her	eby
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica invention by the above application of substitutes, or extensions thereof, ar	nd to any and all improvement ition and, in and to, all Letters r any continuations, continuati	ts which are d Patent to be o on-in-part. div	sclosed in the btained for said sions, renewals	ĒΕ
l hereby covenant that no assignmen entered into which would conflict wit	nt, sale, agreement or encumb h this assignment;	orance has be	en or will be made	or
further covenant that ASSIGNEE wand documents relating to said inverknown and accessible to I and will terelated thereto and will promptly exe	ntion and said Letters Patent a estify as to the same in any inte	ind legal equiverference, litiq	alents as may be	s

Page 3 of 10

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maintain, is equivalents	ives any and all papers, instruments or af sue and enforce said application, said inv thereof which may be necessary or desin SS WHEREOF, I have hereunto set hand	ention and said L able to carry out	etters Patent and sa			
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.						
LEGAL NAI	ME OF INVENTOR(ASSIGNOR)					
Inventor:	Chin-Wei Wu	Date:	AUG 0 1 201	7		
Signature:	Chin-Wei Wu		,			

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NPO#NAU-P3106-USA:0 CUST#UMCF-2017-0083

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In consideration of the payment by	UNITED MICROELECTRON	NICS having a postal	address of
No.3, Li-Hsin Road 2, Science	-Based Industrial Park, Hsi	n-Chu City 300, Taiv	wan, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar	o I of the sum of One Dollar (\$ 1.0 nd valuable consideration.	00), the receipt of which i	is hereby
In consideration of the payment by	Fujian Jinhua Integrated C Co., Ltd.	ircuit having a postal	l address of
6th floor, Podium of electric p Quanzhou City, Fujian provin	ower company building, M ce 362200, P.R.C.	eiling street, Jinjian	g city,
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar	o I of the sum of One Dollar (\$ 1.0 ad valuable consideration.	0), the receipt of which i	is hereby
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica invention by the above application or substitutes, or extensions thereof, ar	nd to any and all improvements w tion and, in and to, all Letters Pat r any continuations, continuation-i	hich are disclosed in the ent to be obtained for sa n-part, divisions, renewa	e aid als.
I hereby covenant that no assignmer entered into which would conflict with	nt, sale, agreement or encumbran n this assignment;	ce has been or will be m	nade or
I further covenant that ASSIGNEE wand documents relating to said inverknown and accessible to I and will terelated thereto and will promptly exe	ition and said Letters Patent and stify as to the same in any interfe	legal equivalents as may rence, litigation proceed	/ be

Page 5 of 10

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maintain, is equivalents	ives any and all papers, instruments or affida sue and enforce said application, said invent thereof which may be necessary or desirable SS WHEREOF, I have hereunto set hand ar	ion and said e to carry ou	Letters Patent and sa	
	oplication data sheet (PTO/SB/14 or equivale ntity, must accompany this form. Use this form		naming the entire	
LEGAL NA	ME OF INVENTOR(ASSIGNOR)			
Inventor:	Tien-Chen Chan	Date:	AUG 0 1 2017	
Signature:	Twee Chen Chan			

Page 6 of 10

NPO#NAU-P3106-USA:0 CUST#UMCF-2017-0083

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The above-identified application was	made or authorized to be made	by me.		
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I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified application or substitutes, or extensions thereof, an	nd to any and all improvements w tion and, in and to, all Letters Pat any continuations, continuation-i	hich are ent to be n-part. o	disclosed in the obtained for salivisions, renew	e aid <i>r</i> als
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or encumbran nthis assignment;	ce has I	peen or will be	made or
I further covenant that ASSIGNEE wi and documents relating to said inven known and accessible to I and will te related thereto and will promptly exec	tion and said Letters Patent and l stify as to the same in any interfe	legal eq rence, li	uivalents as ma tigation procee	av be

Page 7 of 10

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representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof. IN WINTNESS WHEREOF, I have hereunto set hand and seal this AUG 0 1 2017 (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Ger-Pin Lin Date: AUG 0 1 2017

Signature: Ger-Pin Lin Date: AUG 0 1 2017

Page 8 of 10

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I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified application or substitutes, or extensions thereof, an	d to any and all improvements ion and, in and to, all Letters Pa any continuations, continuation	which are atent to be i-in-part. o	disclosed in to botained for divisions, rene	he said wals	
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I further covenant that ASSIGNEE wi and documents relating to said inven known and accessible to I and will tee related thereto and will promptly exec	tion and said Letters Patent and stify as to the same in any interi	d legal equiference. Ii	uivalents as m tigation proce	nav be	

Page 9 of 10

(Date of signing)

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NPO#NAU-P3106-USA:0 CUST#UMCF-2017-0083

RECORDED: 08/08/2017

F#NPO-P0002E-US1201 DSB0-106U017361

PATENT REEL: 043236 FRAME: 0170